

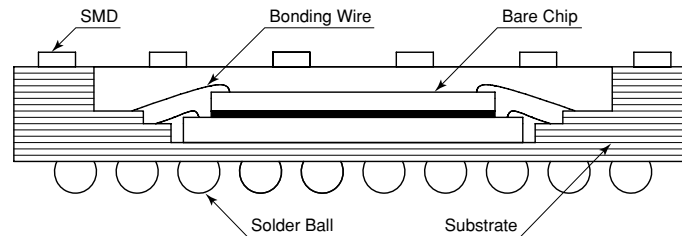
# HYBRID IC

## MULTI CHIP MODULE · SYSTEM IN PACKAGE

### MCM



### CONSTRUCTION



### FEATURES

- Several semiconductors in one package offers downsized system with high performance and standardization
- Wiring space saving by multilayer fine patterns on build-up substrate. No signal delay by shortened wiring distance
- Development with surface mounting type Hybrid IC to consolidate SMD parts
- High precision modules by function trimming
- Less mounting problem because of the decreasing number of terminals

### MOUNTING SPECIFICATIONS

ITEM	UNIT	MIN.	STD.	MAX.	NOTE
Substrate Dimension	mm	50x20	120x100	320x140	
Substrate Thickness	mm	0.3	—	1.6	
Bare Chip Pad Pitch	μm	100	—	—	
Bare Chip Pad Dimension	μm	70	—	—	
Bare Chip Thickness	mm	0.1	0.2	—	
Molding Height	mm	0.3	1.0	1.2	Height from the chip surface
Wire Length	mm	0.3	—	3.0	
Wire Loop Height	μm	100	200	—	
Wire Diameter	Al Au	200 20	300 25	500 40	for Power Module
Plating		Electical/nonelectrical Au Plating			
Substrate		<ul style="list-style-type: none"> <li>•FR-4</li> <li>•FR-5</li> <li>•Alumnia</li> <li>•LTCC</li> <li>•FPC</li> </ul>			

### PACKAGE SPECIFICATIONS

ITEM	UNIT
Terminal Pitch	0.8mm~
Mountable device	<ul style="list-style-type: none"> <li>• SMD</li> <li>• Bare Chip</li> <li>• Printed Resistor (Trimmable)</li> </ul>
Package	<ul style="list-style-type: none"> <li>• SON</li> <li>• BGA</li> <li>• LGA</li> </ul>
Substrate for Package	<ul style="list-style-type: none"> <li>• FR-4</li> <li>• FR-5</li> <li>• Alumina</li> <li>• LTCC</li> </ul>

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